

Gene-6350

Intel LV Celeron SubCompact Board

Thermal Image Analysis Report

Report NO: 06E080044

Release Date: Dec 14, 2006

2006/12/14

Issue Stamp

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Manager

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Test Engineer

Thermal Image Analysis

I . Model Name: Gene-6350 Rev. A1.11

II . Description: Intel LV Celeron SubCompact Board

III . Date: Dec 14, 2006

IV. Measure Site: AAEON QE Dept.

V. Issued by : Eva Yeh

VI. Equipment:

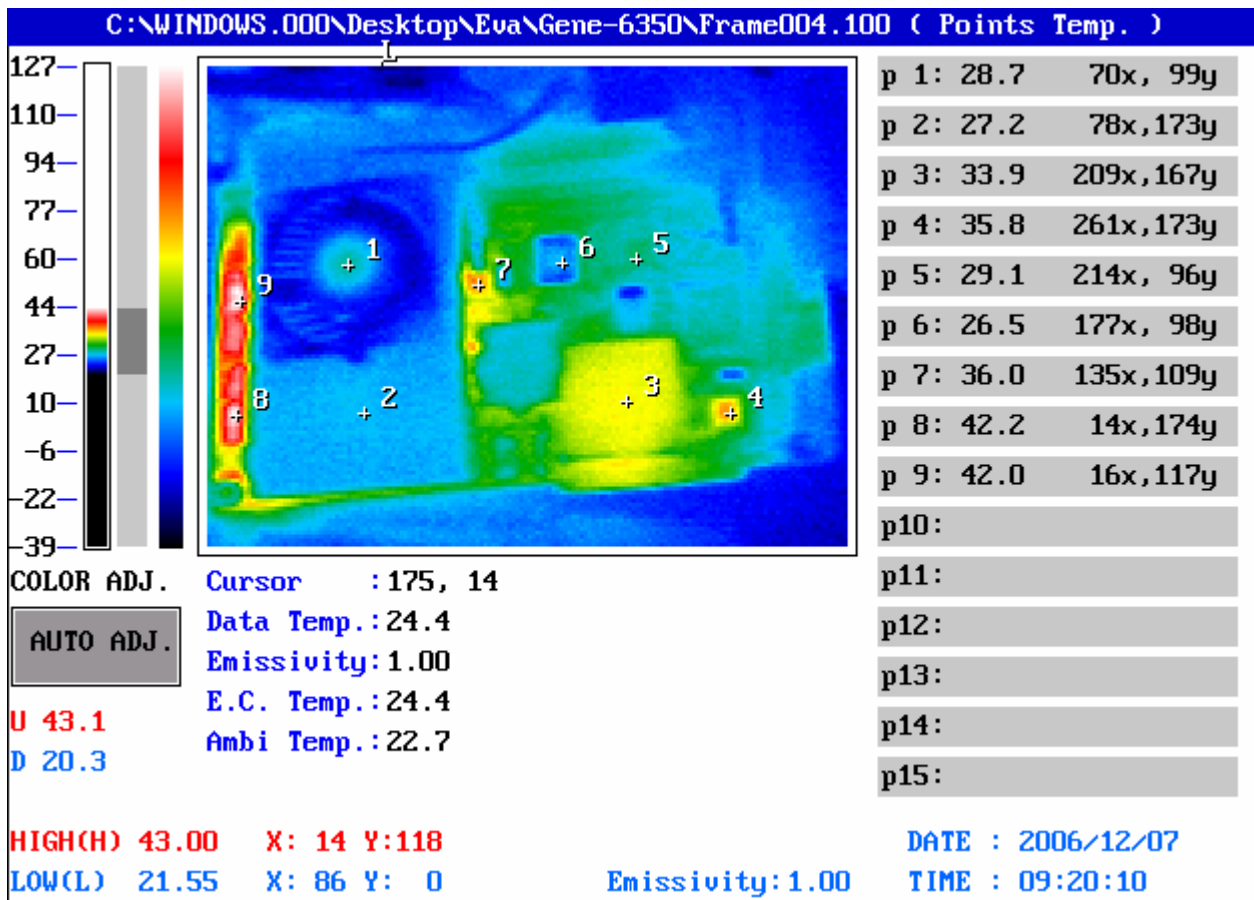
TVS-100 series by NIPPON AVIONICS CO., LTD.

VII. Simulation Environment:

- Temperature: Component Side-1 : 22.7°C , Component Side-2 : 22.1°C ,
- System Configuration :
 - PCB Version : Gene-6350 Rev.A 1.11
- CPU : Intel Ultra Low Voltage Celeron (R) 650MHz CPU
- RAM : Transcend 512MB V58C2256804SAS6 P065397IJAPD
- BIOS : Gene-6350 BIOS Rev:1.5 (11/03/2006)
- CF Card : N/A
- HDD : Maxtor DiamondMax Plus 9 80GB / ATA133
- Application Software: Run Prime95 under Windows XP Professional V2002 Service Pack 2
- Take Picture Time: After Power on 2 hours.

Temperature Profile Test:

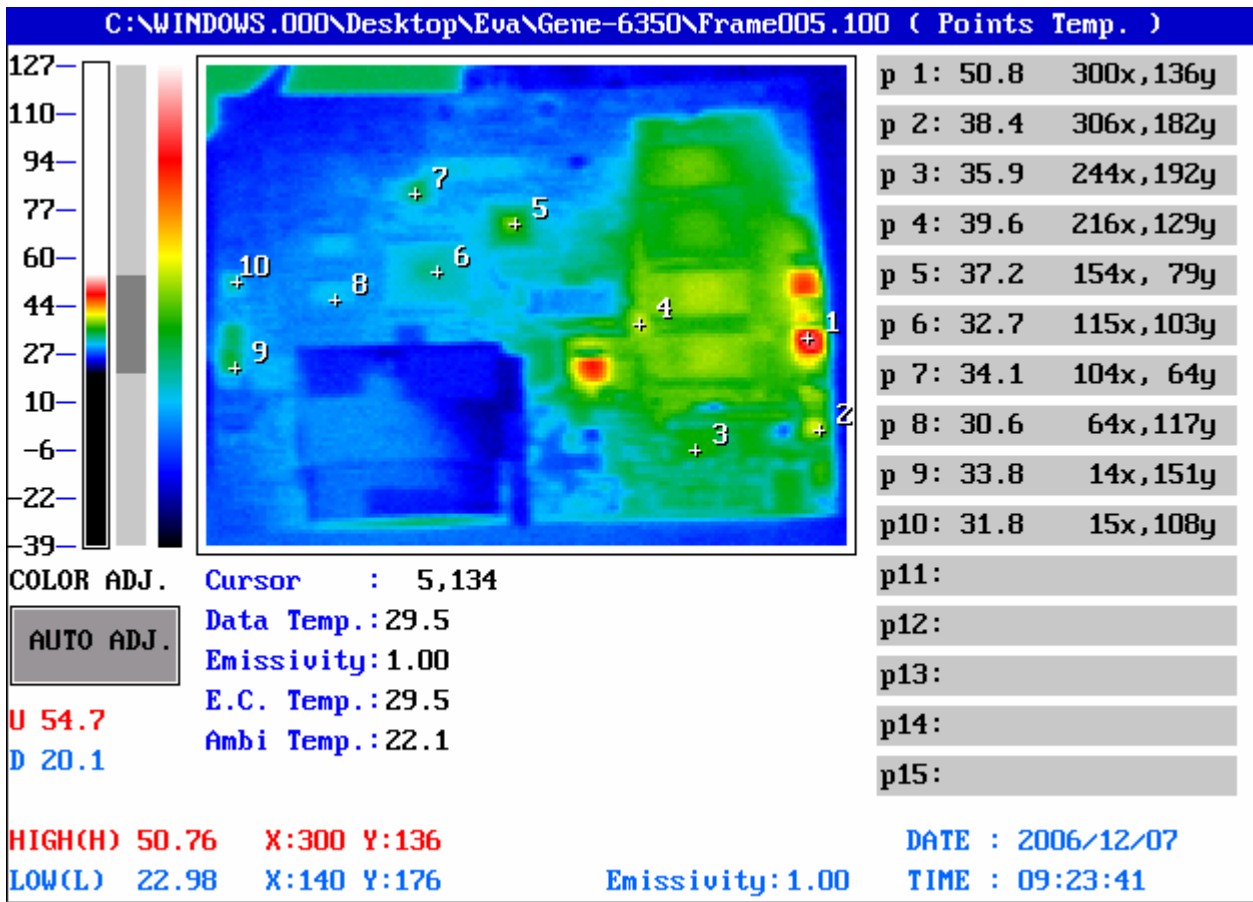
Component Side-1:



Point	Position	Describe	Tc (°C)	Tm (22.7 °C)	Tm (60°C)	Note
1	U13	(TF)IC.SMD.BGA.548P.Rev.CE.Noreh .Bridge Chipset. VIA.VT8623G(CLE266);EE-A050758;14S4862301;TWN	85	28.7	66.0	
2	U3	(TF)INTEL CPU.Celeron.650MHz.Ultra Low Power.MicroFC-BGA.INTEL.NK80530VY650256SL7UJ;EE-A051594;14S4065001;TWN	75	27.2	64.5	
3	U2	(TF)IC.SMD.BGA.487.South Bridge Chipset. VIA.VT8235MG-CD 版;EE-A051648;14S4823501;TWN	85	33.9	71.2	
4	U1	(TF)IC.SMD LQFP 48Pin.6 Channel AC'97 Audio Codec. REALTEK.ALC650;EE-A030738;14S3065001;TWN	85	35.8	73.1	
5	U11	(TF)IC.SMD.Status Monitoring 48Pin LQFP. WINBOND.W83781G;EE-A050824;14S4378101;TWN	100	29.1	66.4	
6	U10	(TF)IC.SMD.LQFP 100P.PCI Ethernet CHIP.RELTEK.RTL8100BL-LF; EE-A050559;14S4810002;TWN	100	26.5	63.8	
7	U9	(TF)IC.FTG for VIA Pro-266 DDR.CYPRESS.CYW3110XC; EE-A060028;14S3031101;TWN	100	36.0	73.3	
8	U5	(TF)PWR.SMD.SO-8.N-Channel 30V 13.8A MOSFET.APEC. AP4424GM;EE-A051480;1315442410;TWN	125	42.2	79.5	
9	U8	(TF)IC.SMD.SO-8P.Dual Operational Amplifiers. NS.LMV358M-NOPB;EE-A030570;14S1035800;TWN	125	42.0	79.3	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
 2. Any Tm value showed in red words which meaning the value is over the Tc+ 5 degree C of this device specification

Component Side-2:



Point	Position	Describe	Tc (°C)	Tm (22.1 °C)	Tm (60°C)	Note
1	Q13	(TF)PWR.SMD.TO-252.N-Channel Power MOSFET. APEC.AP9916GH;EE-A040445;1315991610;TWN	125	50.8	88.7	
2	U19	(TF)IC.SMD SOP.8Pin Switching PWM Controller.Intersil. ISL6520ACBZ;EE-A020421;14S2652000;TWN	100	38.4	76.3	
3	C243	(TF)SP CAP.[8.2µF~470µF].[2V~8V].20%.SMD.Panasonic. EE/ECG 系列(耐溫 260°C);EE-A060158;118*****8*;TWN	105	35.9	73.8	
4	U23	(TF)IC.SMD.SSOP 28P.12 Output Buffer.CYPRESS. CYW2560XC;EE-A060022;14S4025601;TWN	100	39.6	77.5	
5	U34	(TF)IC.SMD.TQFP 64P.DVI Transmitter. VIA.VT1632G;EE-A040477;14S4163200;TWN	85	37.2	75.1	
6	U27	(TF)IC.SMD.TQFP 128P.Super I/O. Winbond.W83697UG;EE-A050783;14S4369701;TWN	100	32.7	70.6	
7	D4	(TF)D Schottky.20V.1A.SMAJ.MCC.SS12; EE-A990224;1300581740;	100	34.1	72.0	
8	U26	(TF)IC.SMD SSOP 28P.RS232 Driver ESD 15KV.INTERASIL. HIN213ECAZ;EE-A000060;14S4021310;TWN	125	30.6	68.5	
9	U21	(TF)PWR.SMD.SO-8 N-Channel 30V 10A MOSFET. CET.CEM4410A(Z);EE-A020990;1315441011;TWN	125	33.8	71.7	
10	U28	(TF)IC.SMD SOP.8Pin Switching PWM Controller. IR.IRU3037CSPbF;EE-A020732;14S2303700;TWN	100	31.8	69.7	

1. Tm (Measured operation temperature) must be less than Tc (Specified case temperature) +5 degree C
 2. Any Tm value showed in **red words** which meaning the value is over the Tc+ 5 degree C of this device specification